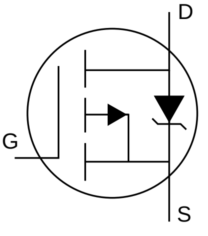
PD - 9.1385A

International
IOR Rectifier

IRF5305

HEXFET® Power MOSFET

- Advanced Process Technology
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- P-Channel
- Fully Avalanche Rated



V_{DSS} = -55V

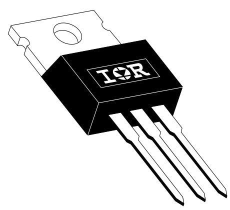
$R_{DS(on)}$ = 0.06Ω

I_D = -31A

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



TO-220AB

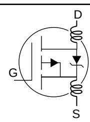
Absolute Maximum Ratings

	Parameter	Max.	Units
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ -10V	-31	A
I_D @ T_C = 100°C	Continuous Drain Current, V_{GS} @ -10V	-22	
I_{DM}	Pulsed Drain Current ①	-110	
P_D @T_C = 25°C	Power Dissipation	110	W
	Linear Derating Factor	0.71	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy②	280	mJ
I_{AR}	Avalanche Current①	-16	A
E_{AR}	Repetitive Avalanche Energy①	11	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-5.0	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting torque, 6-32 or M3 srew	10 lbf•in (1.1N•m)	

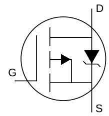
Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{θJC}$	Junction-to-Case	——	1.4	°C/W
$R_{θCS}$	Case-to-Sink, Flat, Greased Surface	0.50	——	
$R_{θJA}$	Junction-to-Ambient	——	62	

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-55	——	——	V	V_{GS} = 0V, I_D = -250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	——	-0.034	——	V/°C	Reference to 25°C, I_D = -1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	——	——	0.06	Ω	V_{GS} = -10V, I_D = -16A ④
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	——	-4.0	V	V_{DS} = V_{GS}, I_D = -250µA
g_{fs}	Forward Transconductance	8.0	——	——	S	V_{DS} = -25V, I_D = -16A
I_{DSS}	Drain-to-Source Leakage Current	——	——	-25	µA	V_{DS} = -55V, V_{GS} = 0V
		——	——	-250		V_{DS} = -44V, V_{GS} = 0V, T_J = 150°C
I_{GSS}	Gate-to-Source Forward Leakage	——	——	100	nA	V_{GS} = 20V
	Gate-to-Source Reverse Leakage	——	——	-100		V_{GS} = -20V
Q_g	Total Gate Charge	——	——	63	nC	I_D = -16A
Q_{gs}	Gate-to-Source Charge	——	——	13		V_{DS} = -44V
Q_{gd}	Gate-to-Drain ("Miller") Charge	——	——	29		V_{GS} = -10V, See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	——	14	——	ns	V_{DD} = -28V
t_r	Rise Time	——	66	——		I_D = -16A
$t_{d(off)}$	Turn-Off Delay Time	——	39	——		R_G = 6.8Ω
t_f	Fall Time	——	63	——		R_D = 1.6Ω, See Fig. 10 ④
L_D	Internal Drain Inductance	——	4.5	——	nH	Between lead, 6mm (0.25in.) from package and center of die contact  D G S
L_S	Internal Source Inductance	——	7.5	——		
C_{iss}	Input Capacitance	——	1200	——	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	——	520	——		V_{DS} = -25V
C_{rss}	Reverse Transfer Capacitance	——	250	——		f = 1.0MHz, See Fig. 5

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	——	——	-31	A	MOSFET symbol showing the integral reverse p-n junction diode.  D G S
I_{SM}	Pulsed Source Current (Body Diode) ①	——	——	-110		
V_{SD}	Diode Forward Voltage	——	——	-1.3	V	T_J = 25°C, I_S = -16A, V_{GS} = 0V ④
t_{rr}	Reverse Recovery Time	——	71	110	ns	T_J = 25°C, I_F = -16A
Q_{rr}	Reverse RecoveryCharge	——	170	250	nC	di/dt = -100A/µs ④

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

② V_{DD} = -25V, starting T_J = 25°C, L = 2.1mH R_G = 25Ω, I_{AS} = -16A. (See Figure 12)

③ $I_{SD} \leq$ -16A, di/dt ≤ -280A/µs, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq$ 175°C

④ Pulse width ≤ 300µs; duty cycle ≤ 2%.

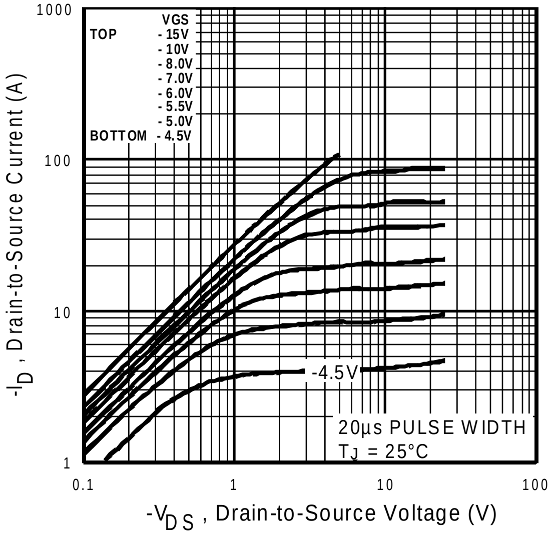


Fig 1. Typical Output Characteristics

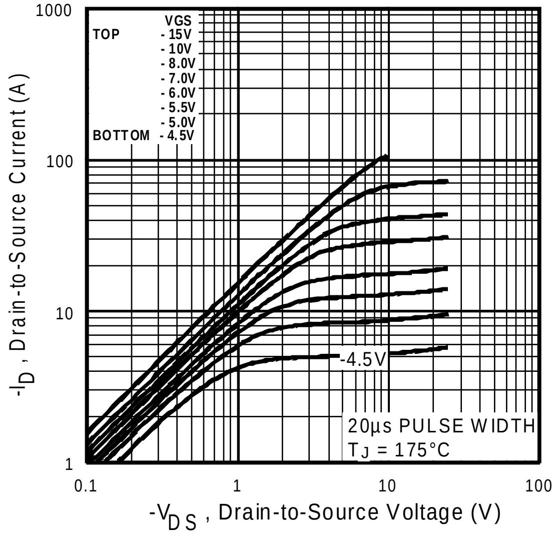


Fig 2. Typical Output Characteristics

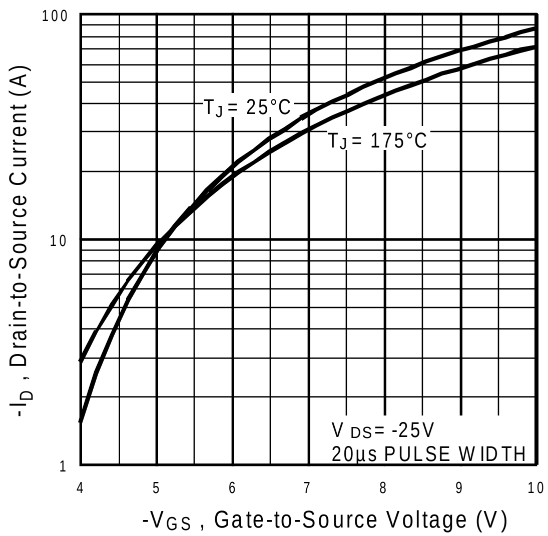


Fig 3. Typical Transfer Characteristics

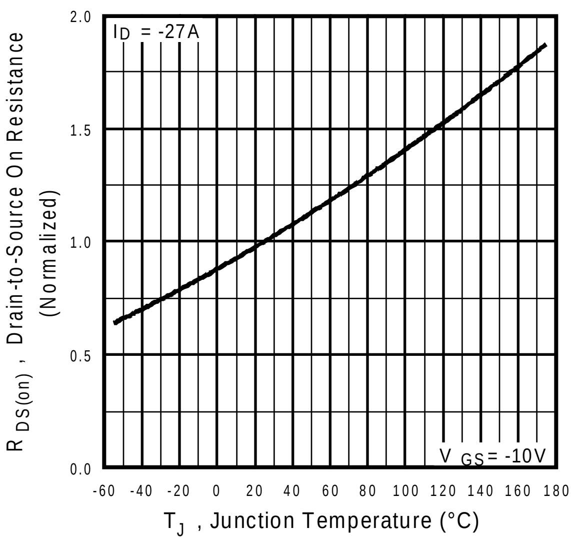


Fig 4. Normalized On-Resistance Vs. Temperature

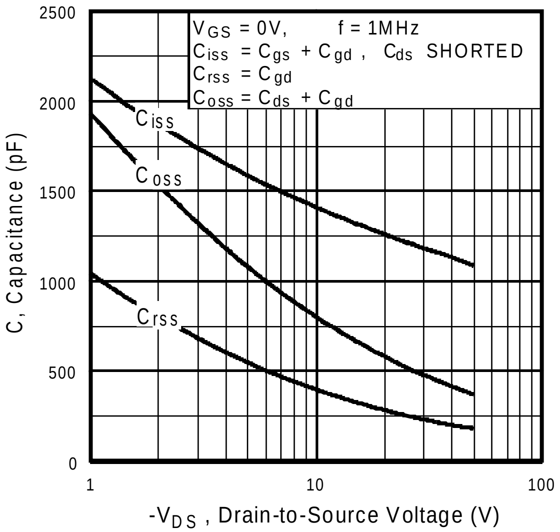


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

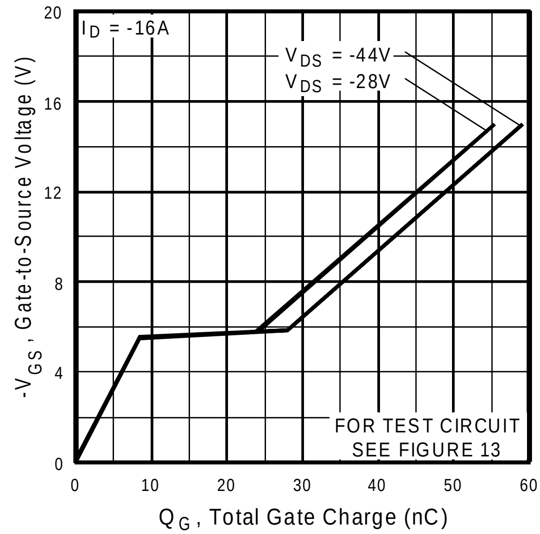


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

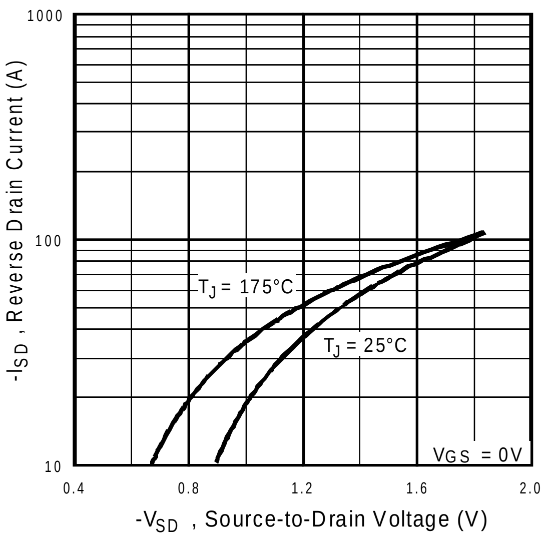


Fig 7. Typical Source-Drain Diode Forward Voltage

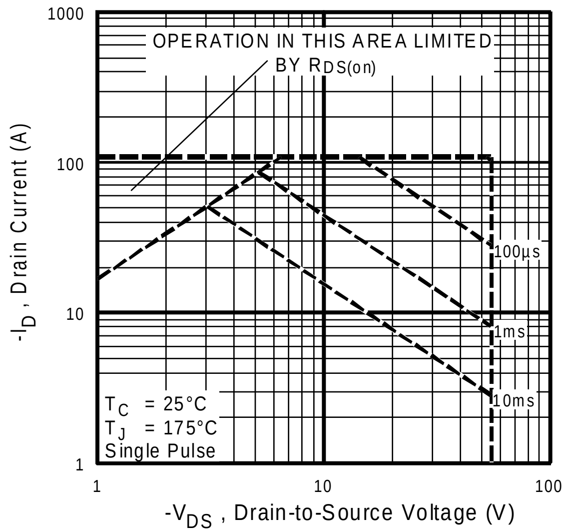


Fig 8. Maximum Safe Operating Area

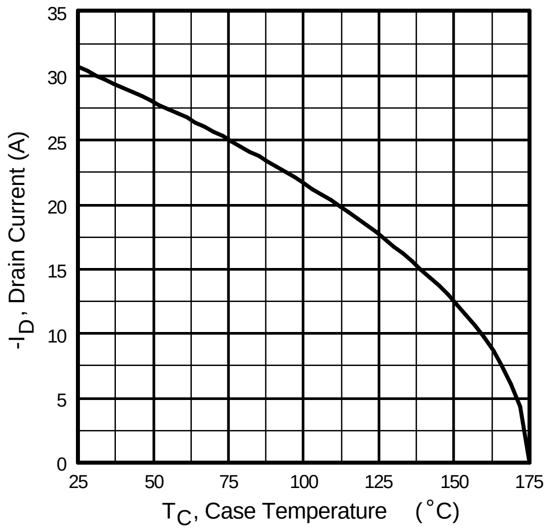


Fig 9. Maximum Drain Current Vs. Case Temperature

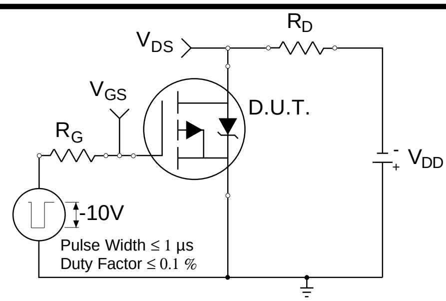


Fig 10a. Switching Time Test Circuit

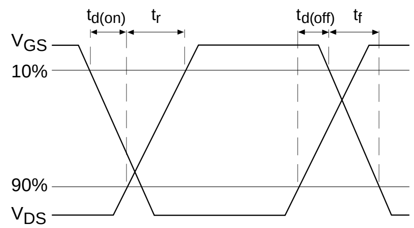


Fig 10b. Switching Time Waveforms

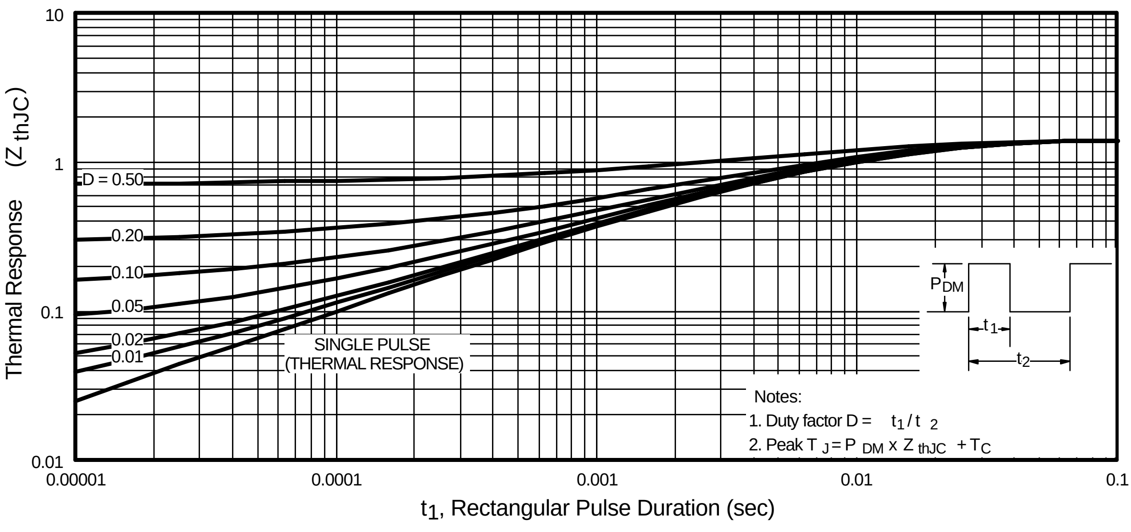


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

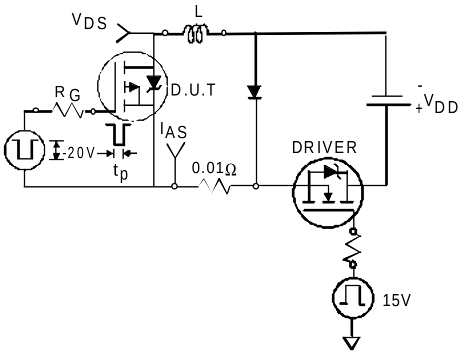


Fig 12a. Unclamped Inductive Test Circuit

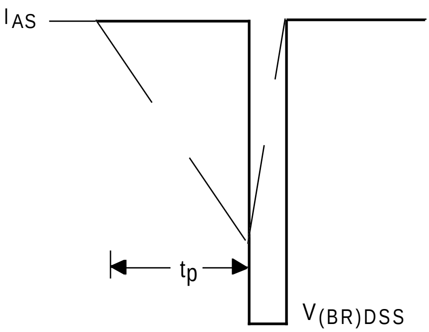


Fig 12b. Unclamped Inductive Waveforms

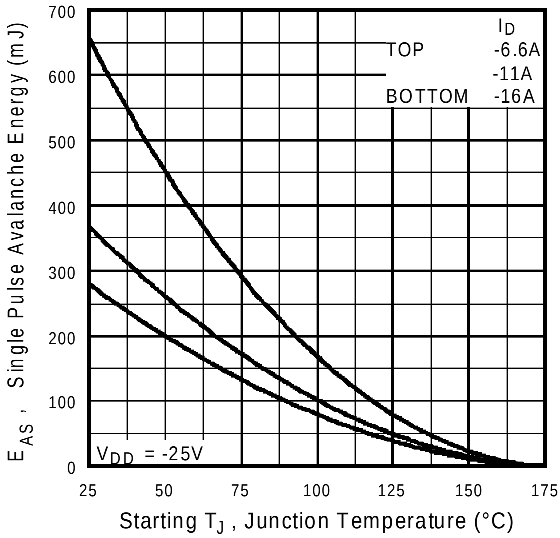


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

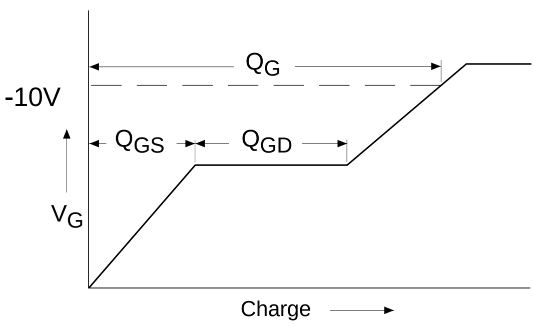


Fig 13a. Basic Gate Charge Waveform

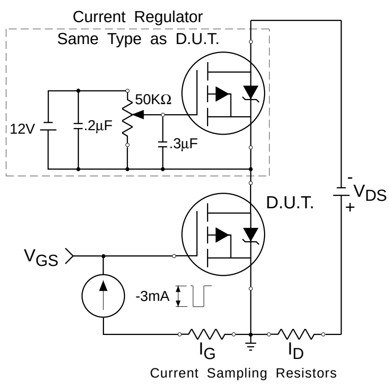
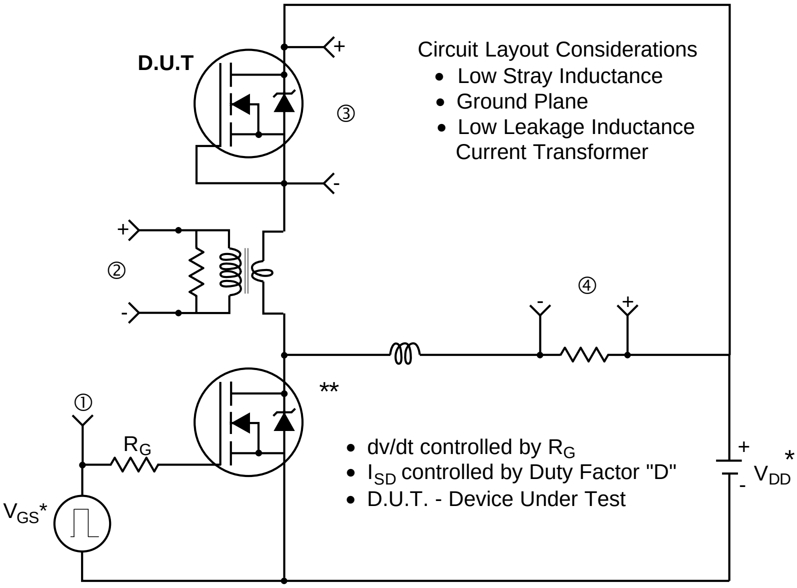
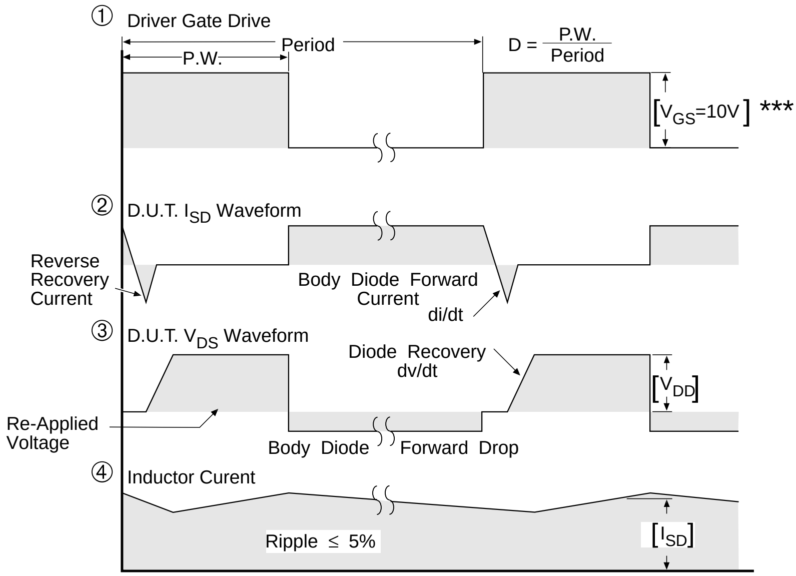


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



* Reverse Polarity for P-Channel
** Use P-Channel Driver for P-Channel Measurements



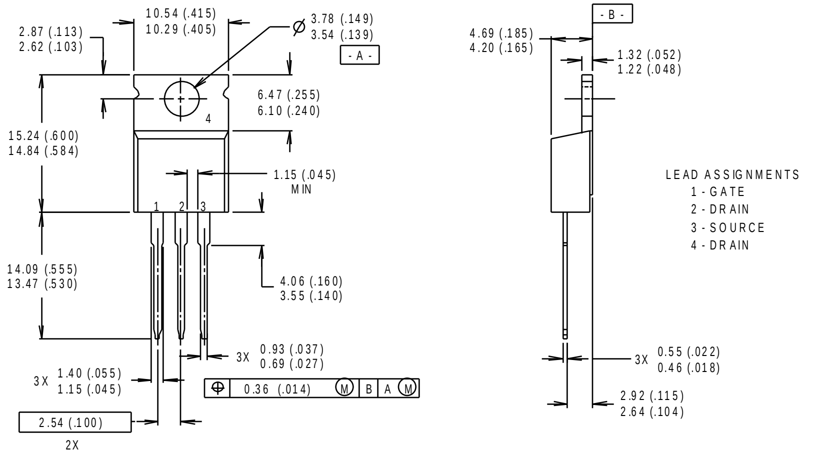
*** V_{GS} = 5.0V for Logic Level and 3V Drive Devices

Fig 14. For P-Channel HEXFETS

Package Outline

TO-220AB Outline

Dimensions are shown in millimeters (inches)



NOTES:

1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.

2 CONTROLLING DIMENSION : INCH

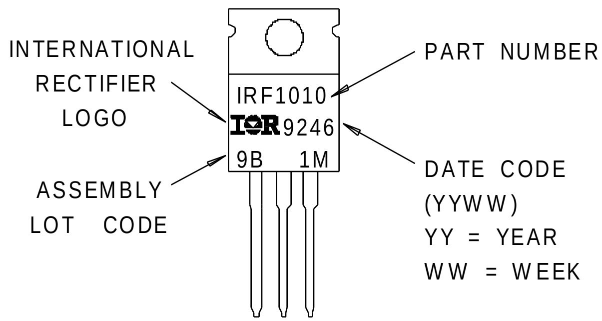
3 OUTLINE CONFORMS TO JEDEC OUTLINE TO-220AB.

4 HEATSINK & LEAD MEASUREMENTS DO NOT INCLUDE BURRS.

Part Marking Information

TO-220AB

EXAMPLE : THIS IS AN IRF1010
WITH ASSEMBLY
LOT CODE 9B1M



International
IOR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331
EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020
IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897
IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111
IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo Japan 171 Tel: 81 3 3983 0086
IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371